Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	72	438/381,382,382,384,385.ccls. and ((dop$5 or implant$6) same (vertical or protru$5))	USPAT	OR	ON	2005/09/13 08:48
L2	313	((((dop$5 or implant$6) and (vertical or protru$5) and ((fin or vertical) adj (structures or devices))) and semiconductor) and resistor) and @ad<="20020128"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 08:48
L3	66	438/381,382,382,384,385.ccls. and ((dop$5 or implant$6) same (vertical or protru$5)) and @ad<="20020128"	USPAT	OR	ON	2005/09/13 09:32
L5	95	(257/542).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/13 10:31
L6	97	257/542,543,536,548,549,550, 308,722.ccls. and ((dop$5 or implant$6) same (vertical or protru$5)) and @ad<="20020128"	USPAT	OR	ON	2005/09/13 12:15
L7	114	257/542,543,536,548,549,550, 308,722.ccls. and ((dop$5 or implant$6) same (vertical or protru$5)) and @ad<="20020128"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 09:33
L9	273	(257/543).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/13 10:36
L10	643	(257/302).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/13 10:37
L11	420	(257/308).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/13 10:51

L12	1359	(257/536).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/13 13:30
L17	62	(257/548).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/13 13:30
L18	126	(257/549).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/13 13:30
L19	76	(257/550).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/13 13:30
S1	74	438/381,382,382,384,385.ccls. and ((dop$5 or implant$6) same (vertical or protru$5)) and @ad<="20020128"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/11/26 12:48
S2	128	438/381,382,382,384,385,238. ccls. and ((dop$5 or implant$6) same (vertical or protru$5)) and @ad<="20020128"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/11/26 12:50
S3	0	438/381,382,382,384,385,238. ccls. and ((dop$5 or implant$6) same (vertical or protru$5)) and (saturat$5 same (unsaturat$5 or (un-saturat$5))) and @ad<="20020128"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/11/26 12:51
S4	0	438/381,382,382,384,385,238. ccls. and ((dop$5 or implant$6) same (vertical or protru$5)) and (saturat$5 same unsaturat$5) and @ad<="20020128"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/11/26 12:52
S5	8	438/381,382,382,384,385,238. ccls. and ((dop$5 or implant$6) same (vertical or protru$5)) and (saturat$5) and @ad<="20020128"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/08 09:47

S6	0	257/722.ccls. and ((dop$5 or implant$6) same (vertical or protru$5)) and (saturat$5) and @ad<="20020128"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/11/26 12:57
S7	311	(438/381).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/12/20 11:02
S8	258	(438/384).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/11/21 08:18
S9	533	(438/385).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/11/21 08:18
S10	77	(438/383).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/11/21 08:18
S11	196	(438/382).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/11/21 09:18
S12	315	(438/381).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2002/12/20 11:03
S13	263	(438/384).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2002/12/20 11:03
S14	203	(438/385).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2002/12/20 11:03
S15	77	(438/383).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/08 13:33
S16	201	(438/382).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2002/12/27 15:37

S17	1164	438/381,382,382,384,385.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/12/27 15:48
S18	860	438/381,382,382,384,385.ccls. and (dop$5 or implant$6)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/12/20 13:46
S19	168	(438/381,382,382,384,385.ccls. and (dop$5 or implant$6)) and (vertical or protru$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/12/27 15:48
S20	5	((438/381,382,382,384,385.ccls. and (dop$5 or implant$6)) and (vertical or protru$5)) and ((fin or vertical) adj structure)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/06/04 14:31
S21	17	((438/381,382,382,384,385.ccls. and (dop$5 or implant$6)) and (vertical or protru$5)) and ((fin or vertical) adj (structure or resistor))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/12/20 15:43
S22	5	((438/381,382,382,384,385.ccls. and (dop$5 or implant$6)) and (vertical or protru$5)) and ((fin or vertical) adj structure)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/12/27 15:27
S23	11	(("3798753") or ("4065742") or ("4191964") or ("4743565") or ("4893166") or ("5172211") or ("5705414") or ("5916821") or ("6072220") or ("6165861") or ("6165862")).PN.	USPAT; USOCR	OR	OFF	2002/12/27 15:39
S24	762	438/381,382,382,384,385.ccls.	USPAT	OR	ON	2002/12/27 15:48
S25	57	438/381,382,382,384,385.ccls. and ((dop$5 or implant$6) same (vertical or protru$5))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/12/27 15:49
S26	57	438/381,382,382,384,385.ccls. and ((dop$5 or implant$6) same (vertical or protru$5))	USPAT	OR	ON	2005/09/13 08:47
S27	1	("6300180").PN.	USPAT; USOCR	OR	OFF	2003/11/19 10:49

S28	748	(438/238).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/08 12:50
S29	1492	(dop$5 or implant$6) and (vertical or protru$5) and ((fin or vertical) adj (structures or devices))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/06/04 14:34
S30	407	(dop$5 or implant$6) same ((vertical or protru$5 or fin) adj (structures or devices))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/06/04 14:35
S31	1367	((dop$5 or implant$6) and (vertical or protru$5) and ((fin or vertical) adj (structures or devices))) and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/06/04 14:35
S32	342	((dop$5 or implant$6) same ((vertical or protru$5 or fin) adj (structures or devices))) and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/06/10 09:22
S33	303	(((dop$5 or implant$6) and (vertical or protru$5) and ((fin or vertical) adj (structures or devices))) and semiconductor) and resistor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/06/04 14:46
S34	73	(((dop$5 or implant$6) same ((vertical or protru$5 or fin) adj (structures or devices))) and semiconductor) and resistor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/06/04 14:47
S35	63	((((dop$5 or implant$6) same ((vertical or protru$5 or fin) adj (structures or devices))) and semiconductor) and resistor) and @ad<="20020128"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/06/04 14:48
S36	288	((((dop$5 or implant$6) and (vertical or protru$5) and ((fin or vertical) adj (structures or devices))) and semiconductor) and resistor) and @ad<="20020128"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 08:48
S37	4	(((((dop$5 or implant$6) same ((vertical or protru$5 or fin) adj (structures or devices))) and semiconductor) and resistor) and @ad<="20020128") and fin	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/06/04 15:06

S38	14	((((((dop$5 or implant$6) and (vertical or protru$5) and ((fin or vertical) adj (structures or devices))) and semiconductor) and resistor) and @ad<="20020128") and fin	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/06/04 15:08
S39	934	(257/722).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/06/05 08:43
S40	14	257/722.ccls. and (dop$6 or implant$6)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/06/05 08:44
S41	1586	((vertical or protru$5 or fin) adj (structures or devices)) and (dop$5 or implant$6) and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/06/10 09:24
S42	1483	((vertical or protru$5 or fin) adj (structures or devices)) and (dop$5 or implant$6) and semiconductor and @ad <="20020128"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/06/10 09:25
S43	121	(((vertical or protru$5 or fin) adj (structures or devices)) with (dop$5 or implant$6)) and semiconductor and @ad <="20020128"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/06/10 09:29
S44	310	(((vertical or protru$5 or fin) adj (structures or devices)) same (dop$5 or implant$6)) and semiconductor and @ad <="20020128"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/11/19 10:47
S45	2	(("4893166") or ("4416049")).PN.	USPAT; USOCR	OR	OFF	2003/06/16 08:05
S46	45	(((vertical or protru$5 or fin) adj (structures or devices)) same (dop$5 or implant$6)) and semiconductor and @ad <="20020128" and saturat$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/08 12:50
S47	1	("20030141569").PN.	US-PGPUB; USOCR	OR	OFF	2003/11/19 10:49
S50	4	(("6171910") or ("6251729") or ("6368915") or ("6406963")).PN.	USPAT; USOCR	OR	OFF	2002/11/21 10:28
S52	2	(("6274408") or ("5789270")).PN.	USPAT; USOCR	OR	OFF	2002/12/30 10:08

S54	1	("4893166").PN.	USPAT; USOCR	OR	OFF	2003/06/16 08:05
S55	9	438/381,382,382,384,385,238. ccls. and ((dop$5 or implant$6) same (vertical or protru$5)) and (saturat$5) and @ad<="20020128"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/08 09:49
S56	0	(438/381,382,382,384,385,238. ccls. and ((dop$5 or implant$6) same (vertical or protru$5)) and (saturat$5)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/08 09:50
S57	0	(438/381,382,382,384,385,238. ccls. and ((dop$5 or implant$6) same (vertical or protru$5)) and (saturat$5)).clm.	US-PGPUB; USPAT	OR	ON	2005/09/08 09:50
S58	0	(438/381,382,382,384,385,238. ccls. and ((dop$5 or implant$6) same (vertical or protru$5)) and (saturat$5)).clm.	US-PGPUB	OR	ON	2005/09/08 09:50
S59	0	("438"/$.ccls. and ((dop$5 or implant$6) same (vertical or protru$5)) and (saturat$5)).clm.	US-PGPUB	OR	ON	2005/09/08 09:50
S60	0	("257"/$.ccls. and ((dop$5 or implant$6) same (vertical or protru$5)) and (saturat$5)).clm.	US-PGPUB	OR	ON	2005/09/08 09:50
S61	8	(semiconductor and ((dop$5 or implant$6) same (vertical or protru$5)) and (saturat$5)).clm.	US-PGPUB	OR	ON	2005/09/08 09:52
S62	9	(semiconductor and ((dop$5 or implant$6) same (vertical or protru$5)) and (saturat$5)).clm.	USPAT	OR	ON	2005/09/08 09:54
S63	773	((semiconductor and (dop$5 or implant$6)) same (vertical or protru$5)) and (saturat$5)	USPAT	OR	ON	2005/09/08 10:57
S64	6	(((semiconductor and (dop$5 or implant$6)) same (vertical or protru$5)) and (saturat$5)).clm.	USPAT	OR	ON	2005/09/08 09:56
S65	1133	(438/238).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/08 13:14
S66	47	(((vertical or protru$5 or fin) adj (structures or devices)) same (dop$5 or implant$6)) and semiconductor and @ad <="20020128" and saturat$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/08 12:50

S67	34	((((vertical or protru$5 or fin) adj (structures or devices)) same (dop$5 or implant$6)) and semiconductor).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/08 13:12
S68	21	((((vertical or protru$5 or fin) adj (structures or devices)) same (dop$5 or implant$6)) and semiconductor).clm.	US-PGPUB	OR	ON	2005/09/08 12:51
S69	2	("6720231").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/08 13:15
S70	1945	fried.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/08 13:15
S71	150	S70 and david	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/08 13:15
S72	42	S71 and fin	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/08 13:32
S73	9	S72 and @ad<="20020128"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/08 13:32
S74	782	S70 and @ad<="20020128"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/08 13:32
S75	55	S71 and @ad<="20020128"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/08 13:32

S76	9	S75 and fin	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/08 13:32
S77	616	(438/381).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/13 09:31